

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5214693

SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	CORRECTION TO THE SPELLING OF ASSIGNOR'S NAME IN A COVER SHEET PREVIOUSLY RECORDED ON REEL: 031357AND FRAME: 0372. ASSIGNOR(S) HEREBY CONFIRMS THE ASSIGNMENT
RESUBMIT DOCUMENT ID:	504999757

CONVEYING PARTY DATA

Name	Execution Date
HIROSHI FUKAYA	09/28/2013
NAI KANG LIANG	09/28/2013

RECEIVING PARTY DATA

Name:	SAE MAGNETICS (H.K.) LTD
Street Address:	SAE TECHNOLOGY CENTER, 6 SCIENCE PARK EAST AVENUE
Internal Address:	HONG KONG SCIENCE PARK
City:	SHATIN, N.T.
State/Country:	HONG KONG
Name:	SAE TECHNOLOGIES DEVELOPMENT (DONGGUAN) CO. LTD.
Street Address:	WINNERWAY INDUSTRIAL AREA, NANCHENG
Internal Address:	DONGGUAN CITY
City:	GUANGDONG PROVINCE
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13939136

CORRESPONDENCE DATA**Fax Number:**

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: charles_ho@barron-young.com

Correspondent Name: B.Y.I.P., LTD

Address Line 1: P.O. BOX 1484

Address Line 2: GENERAL POST OFFICE

Address Line 4: HONG KONG, HONG KONG

ATTORNEY DOCKET NUMBER:	CLOUD-1808-USPT
NAME OF SUBMITTER:	CHARLES HO

SIGNATURE:	/Charles Ho/
DATE SIGNED:	10/31/2018
Total Attachments: 5 source=original cover sheets and originally recorded assignment_CLOUD-1808-USPT#page2.tif source=original cover sheets and originally recorded assignment_CLOUD-1808-USPT#page3.tif source=original cover sheets and originally recorded assignment_CLOUD-1808-USPT#page4.tif source=original cover sheets and originally recorded assignment_CLOUD-1808-USPT#page5.tif source=original cover sheets and originally recorded assignment_CLOUD-1808-USPT#page6.tif	

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EPAS ID: PAT2568396

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HIROSHI FUKAYA</td> <td>09/28/2013</td> </tr> <tr> <td>NAI LANG LIANG</td> <td>09/28/2013</td> </tr> </tbody> </table>		Name	Execution Date	HIROSHI FUKAYA	09/28/2013	NAI LANG LIANG	09/28/2013				
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CORRESPONDENCE DATA											
Fax Number:	(949)253-0902										
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Address Line 4:	IRVINE, CALIFORNIA 92614										

CH \$40.00 13939136

502523220

PATENT
 REEL: 031357 FRAME: 0372

PATENT
 REEL: 047375 FRAME: 0968

ATTORNEY DOCKET NUMBER:	1958785.00002
NAME OF SUBMITTER:	KIMBERLEY G. NOBLES
Signature:	/Kimberley G. Nobles/
Date:	10/07/2013
Total Attachments: 3 source=1958785_00002_US_EXECUTED_ASSIGNMENT#page1.tif source=1958785_00002_US_EXECUTED_ASSIGNMENT#page2.tif source=1958785_00002_US_EXECUTED_ASSIGNMENT#page3.tif	

PATENT
REEL: 031357 FRAME: 0373

PATENT
REEL: 047375 FRAME: 0969

ASSIGNMENT BY INVENTOR

THIS ASSIGNMENT, made by Hiroshi FUKAYA, whose mailing address is: c/o SAE Technology Center, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T., Hong Kong; and Nai Kang LIANG, whose mailing address is: c/o SAE Technologies Development (Dongguan) Co., Ltd., Winnerway Industrial Area, Nancheng, Dongguan City, Guangdong Province, China, (hereinafter referred to as Assignors),;

WHEREAS, Assignors have invented certain new and useful improvements in OPTICAL MODULE PACKAGE, set forth in a Patent application for Letters Patent of the United States, already filed on July 10, 2013 as U.S. Application Serial No. 13/939,136; and

WHEREAS, SAE Magnetics (H.K.) Ltd., having its principle place of business at SAE Technology Center, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T., Hong Kong, and SAE Technologies Development (Dongguan) Co., Ltd., having its principle place of business at Winnerway Industrial Area, Nancheng, Dongguan City, Guangdong Province, China, (hereinafter referenced as ASSIGNEES), are jointly (equal shares) desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors, as joint inventors as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other International agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me/us with respect to the filing of applications for patents or securing of patents in the United

States and countries foreign thereto, and Assignors hereby authorize and request the Commissioner of Patents to issue the United States Letters Patent to said ASSIGNEES jointly (equal shares), as the ASSIGNEES of the whole right, title and interest thereto;

AND Assignors further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me/us and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

AND Assignors further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

AND Assignors further agree that ASSIGNEES will, upon request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me/us and will testify as to the same in any interference or litigation related thereto;

AND Assignors hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

AND Assignors hereby authorize and request the attorneys of record in this application to insert the execution date, serial number and filing date of this application in the spaces that follow:

Application Serial Number: 13/939.136 Filing Date: July 10, 2013

This assignment is being executed on the date indicated below.

福后浩

Dated: 2013.9.28

Hiroshi FUKAYA

梁乃康

Dated: Sep. 28 2013

Nai Kang LIANG